

## Space Parts Working Group

### Tuesday, April 13, 2004

7:00am	Registration
8:00am	Welcome and Opening Remarks Dave Davis, SMC Mel Cohen, The Aerospace Corp.
8:10am	Keynote Speaker Col. James Horejsi, SMC
8:40am	Air Force Space and Missile System Center Update Dave Davis, SMC
9:00am	Radiation Hardness Oversight Council (RHOC) John Ingram-Cotton, The Aerospace Corp.
9:15am	One NASA Passive Components Evaluation NASA EEE Parts Mike Sampson, NASA Goddard
10:10	BREAK
10:20am	One NASA PEMs Evaluation Shri Agarwal and Mike Sandor, NASA Jet Propulsion Laboratory
10:50am	Actel FPGA Update Dan Elftmann and John McCollum, Actel
11:40am	Passive Parts Update Jocelyn Siplon, The Aerospace Corp.
12:00	LUNCH BREAK
1:00pm	DTRA Developments Lew Cohn, Defense Threat Reduction Agency
1:20pm	Data Review/Data Retention What We Used To Do/Where We Are Now Dale Cole, D <sup>2</sup> M <sup>2</sup> Corp
1:40pm	NEMI Work to Date on Whisker Testing Jack McCullen, Intel Corp.
2:00pm	IC Supplier Panel Discussion Screening and Qualification of Plastic Encapsulated Microcircuits (PEMs) Mike Tekulve, National Semi Wallace Scott, Texas Instruments Joyce Evens, Vishay Siliconics
3:00pm	BREAK
3:10pm	JPL/NASA Mars Explorer Rover (MER) EEE Parts Program Requirements Kristy Evans, Electronic Parts Engineering Office Manager NASA Jet Propulsion Laboratory
3:30pm	Enhanced Low Dose Rate Sensitivity Mike Maher, National Semiconductor
3:50pm	Supplier Update - Hybrid, MOSFET and Power Controllers Tiva Bussarakons, International Rectifier
4:10pm	Microsemi Consolidations Curt Olson, Microsemi
4:30pm	SEFI Mitigation Chip (H-Core) David Czajkowski, Space Micro
4:50pm	Lead-Free: Dilemma for High Reliability Edward Li, AEM
5:10pm	Semiconductor Update MIL-PRF-19500 Discrete Semiconductors and Changes to Specifications Mel Cohen, The Aerospace Corporation

## **Wednesday, April 14, 2004**

7:00am	Registration
8:00am	Welcome AGENDA Review Dave Davis, SMC
8:10am	Changing Micro Circuit Technology Paul Coe, Aeroflex-UTMC
8:30am	Programmable Space Level Crystal Oscillator Dr. Keith Rouse, Cardinal Components
8:50am	Hermeticity Testing of Small Volume Packages John Pernicka, Pernicka Corp.
9:15am	New Technologies at Microsemi Don Besler, Microsemi Corp.
9:35am	Radiation Test Results for Rad Hard Optocouplers Bill Holmes, Micropac
9:55am	Trends and Challenges As Seen In Destructive Physical Analysis Trevor Devaney, Hi-Rel Labs
10:15am	BREAK
10:25am	Solar Arrays – An Evolving Technology Jennifer Granata, The Aerospace Corp.
10:50am	IC Supplier Paul Nixon, BAE Systems Dan Kagey, Honeywell SSEC
11:30am	Hermeticity/Residual Gas Testing of Small Volume Packages Dan Rossiter, Oneida Research
12:00	LUNCH BREAK
1:00pm	New Developments in Optocoupler Jamshed Khan, Agilent Technologies
1:20pm	Update on Vishay Plant Relocations and Qualification of Components Eric Michaelson, Vishay Tech
1:40pm	Optical Leak Detection Bruce Wilson, NORCOM
2:00pm	A Semicoa Product Update Alan Johnson, Semicoa
2:20pm	A New Connector Entering the Space Market - Compact Peripheral Computer Interconnect, Henry Wong, Northrop Grumman
2:40pm	Silicon Carbide Semiconductors Michael Povey, Sensitron
3:00pm	BREAK
3:10pm	Proposed Revisions to Appendix A of MIL-STD-1547 and Appendix B of MIL-STD-1546 George Cuevas, The Aerospace Corp.
3:30pm	Microcircuit Data Review Larry Harzstark, The Aerospace Corp.
3:50pm	Prohibited Materials – Mitigation Strategies Frank Chong, Northrop Grumman
4:10pm	Hybrid Update Emanuel Bucur, The Aerospace Corp.
4:30pm	Test Facility: A Means To An End C. E. “Bud” McBrayer, Wyle Labs
4:45pm	Adjourn